Barrel Hybrid Production

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Production status

- Produced Hybrids
- Recent problems
- Gold and PA pads contamination
- PA bondability tests
- Pitch-adapter production

Produced hybrids

- From Seiko-Precision ~1900
- Delivered to Sites: 1529

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Site Deliv'd OldPA #?? #26 #27 #28 #29 #30 #35 #36 #54 #59 #60 #61 #62 #63 #64 #65

Japan: 744 166 129 1 - 6 28 46 30 30 52 - 17 37 1 ? ? ?

Nordic: 95 6 5 2.5 6.5 8 4 25 15 6 - 2 - - 12 - -

UK: 360 39 39 - - 14 5 16 28 16 8 4 8 - 42 50 54

US: 330 32 18 - - 16 9 32 45 62 41 - 8 8 - 16 51 69 (no perfect counting)
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SCT week, Tuesday, 2 Dec 2003

Produced hybrids (cont'd)

• HOLD: 392

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Old PA
           122
                  Whiskers
            44
Lot#29
                  White PA, too soft metalization?
Lot#31
              7
                  Seemed good but weak peel
                  Improvement in metalization failed
           104
Lot#55
Lot#61-65
           115
                  #61-Whiskers, #63-64 & 65 - Ar plasma
                  cleaning on PA turned out no good
```

These pitch-adapter(PA)'s are to be replaced

Recent problems

- Gold and PA pads contamination
 - In the recent lot#64/65 deliveries, worse bondability on gold pads in hybrids were reported.
 - Reported more often cleaning of wedge in bonding gold pads in the US
 - Color of gold pads more orange than yellow
 - Contamination on PA of the hybrids also observed
 - Also, bad bondability at UCSC while bondable at LBL on PA

Gold and PA pads contamination

 Gold pads color difference (LBL)

 PA pads contamination in the same hybrid

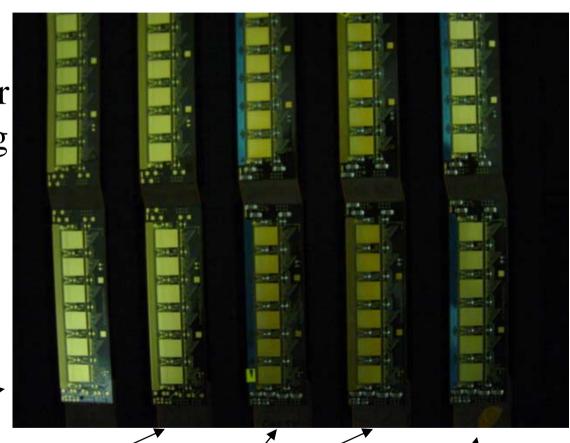






Gold and PA pads contamination

 Coloration was after SMD solder and flux cleaning



Bare flex -

Bridge glued SMD soldered Plasma cleaned

Analysis of gold pad contamination

- SEM 10kV analysis
 - C and O were observed, but no Cu, Ni, and Ag
- Metal thickness analysis (Fluorescent X-ray)

```
#2
                                     #5 Design [um]
         #1
                       #3
                              #4
                                   0.35
        0.39
              0.37
                      0.34
                             0.32
                                           0.3 \sim 0.6
Au
                      5.10
                             5.05
Ni
        4.36
              5.39
                                    4.90
                                            4~6
```

- Bond strength acceleration test (100C, 72 hr, Air)
 - Plasma cleaned, 20 bonds at 12 pads, 3 samples
 - Pull tests: 120 before and 120 after in each sample
 - All heel-breaks, After-Before delta-pull < -0.6 g

Gold pad contamination

- No faulty Ni plating
 - If faulty Ni plating, Cu migration may deteriorate bonds in long term
- Most plausible source is residue of adhesive
 - of protection film during the bridge-flex gluing
 - which absorbed solder flux water and colored or absorbed colored flux water in the cleaning bath (accidentally contaminated)

Gold pad contamination (cont'd)

- Argon plasma cleaning
 - The contamination is easily removed with a short time application of Argon plasma cleaning
 - Unfortunately, plasma cleaning of PA showed detrimental effect on the PA bondability
 - In future shipments, hybrid surface will be plasma cleaned with PA covered.
 - PA cover will be removed and alcohol wipecleaning when contamination is observed. No PA cover in the shipping

Recent problems (cont'd)

- Bondability tests of PA samples
 - In advance of real hybrid delivery, samples of PA's were sent to sites for bondability test
 - Samples included a baseline (thinner) and a thicker metalization (but this confused the tests)
 - Baseline one was acceptable and a thicker
 metalization was at the edge of bondability in Japan
 - Bondability degraded as lot advances, Lot#64 > #65> #67

PA bondability tests

Lot#65 PA samples

Site baseline thicker

Birmingham OK, minor "end" whiskers OK, minor "end" whiskers

RAL Good No stick

RAL (another #65 samples) Good
UCSC 12.3g, OK 12g, higher power

Lot#67 PA samples

Birmingham better, >50% peel worse, >50% peel

UCSC OK, (almost) no whisker, no peel bad, whiskers

higher power higher power

PA bondability tests

Lot#BS PA sample

Birmingham OK, minor whiskers
UCSC higher power, a few peels, fine whiskers

Japan higher power, splash of metal debris

Pitch-adapter production

- Continue selection of PA glasses
 - About 50 glasses in stock in lots of 65, 66, 67, 68
 - Finer sampling (I.e.one sample from one glass)
 - 20 PA's in a glass: if ~20% yield, still ~100 hybrids
- Search for new metalization company
 - Two vendors in Japan
 - One vendor in the US
 - IMB-CNM: endcap vendor

Delivery expectation

- Selection of glasses
 - 1st round was lost (plasma cleaned)
 - 2nd round was shipped (to Birmingham), ~1.5 week
 for transport and evaluation, ~1.5 week for attaching
 and delivery if acceptable glasses: ~3 weeks
- New metalization
 - IMB glasses (10 glasses) delivered
 - One Japanese vendor glasses delivered
 - ~1 week, test samples will be shipped. If good, then
 ~3 weeks: ~4 weeks

Summary

- More than 50% of hybrids are delivered
- Hybrid production is suffering from problems: bondability of PA metalization and recently gold pad contamination
- Gold pad contamination is cleanable with Ar plasma cleaning
- New PA metalization has to be found and the delivery of hybrids depends on the availability of good metalization